

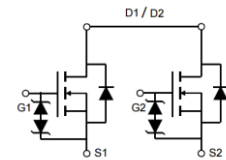
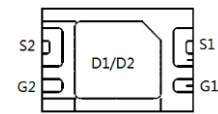
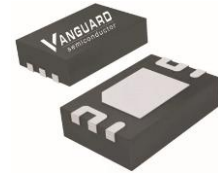
## Features

- N-Channel, 3.3V Logic Level Control
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=3.3V$
- ESD Protection
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant



Part ID	Package Type	Marking	Tape and reel information
VSA007N02ED	TDFN2x3-6L	007N02ED	3000pcs/Reel

$V_{DS}$	20	V
$R_{DS(on),TYP} @ V_{GS}=5.0V$	6.5	m $\Omega$
$R_{DS(on),TYP} @ V_{GS}=3.3V$	7.0	m $\Omega$
$I_D$	12	A

**TDFN2x3-6L**


## Maximum ratings, at $T_j=25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	20	V
$I_S$	Diode continuous forward current	$T_C=25^\circ\text{C}$	12 A
$I_D$	Continuous drain current	$T_C=25^\circ\text{C}$	12 A
		$T_A=100^\circ\text{C}$	7.6 A
$I_{DM}$	Pulse drain current tested ①	$T_C=25^\circ\text{C}$	48 A
EAS	Avalanche energy, single pulsed ②	$L=0.5\text{mH}$	16 mJ
$P_D$	Maximum power dissipation	$T_A=25^\circ\text{C}$	2 W
$V_{GS}$	Gate-Source voltage	$\pm 12$	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 175	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	45	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	62.5	$^\circ\text{C/W}$

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>c</sub> =25°C)	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>c</sub> =125°C)	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	--	--	±10	uA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5	0.8	1.2	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =5.0V, I <sub>D</sub> =5A	--	6.5	9.0	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =3.3V, I <sub>D</sub> =5A	--	7.0	9.5	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =2.5V, I <sub>D</sub> =2A	--	9.0	11.0	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz	--	1310	--	pF
C <sub>oss</sub>	Output Capacitance		--	260	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	235	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =16V, I <sub>D</sub> =11A, V <sub>GS</sub> =4.5V	--	15	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	3	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	7	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =16V, I <sub>D</sub> =5.5A, R <sub>G</sub> =3Ω, V <sub>GS</sub> =4.5V	--	31	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	87	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	69	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	37	--	nS
<b>Source- Drain Diode Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =5A, V <sub>GS</sub> =0V	--	0.70	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25°C, I <sub>sd</sub> =10A, V <sub>GS</sub> =0V di/dt=100A/μs	--	47	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		--	62	--	nC

**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 8A, V<sub>GS</sub> = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

Typical Characteristics

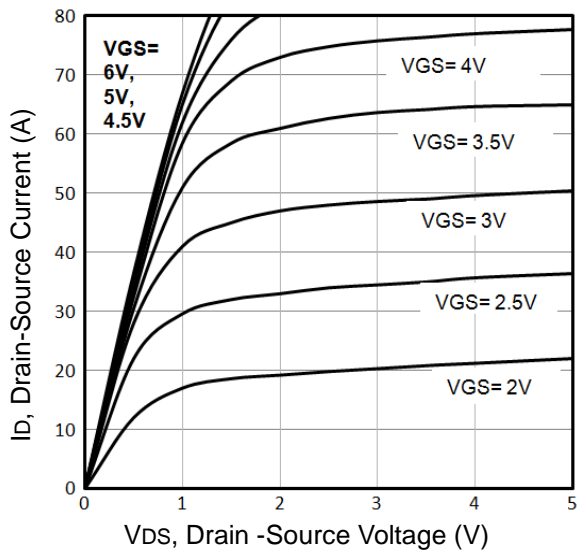


Fig1. Typical Output Characteristics

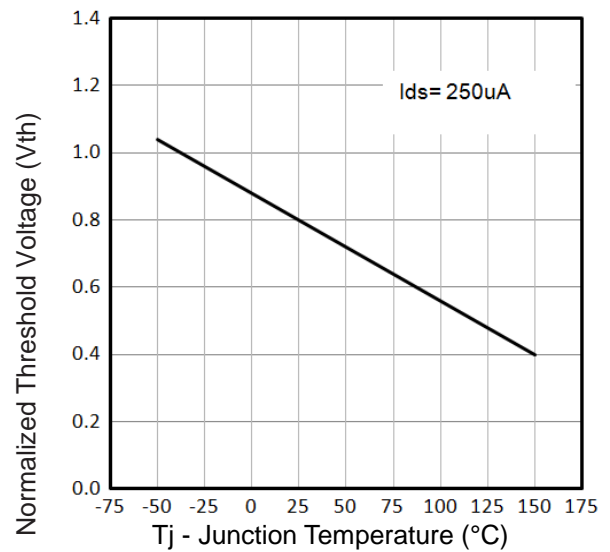


Fig2. Normalized Threshold Voltage Vs. Temperature

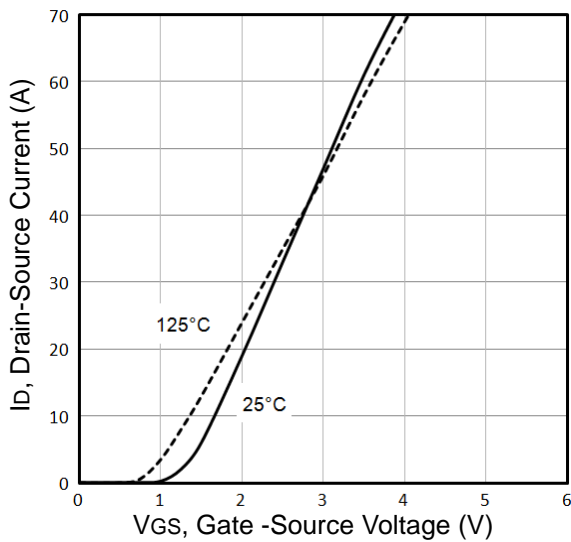


Fig3. Typical Transfer Characteristics

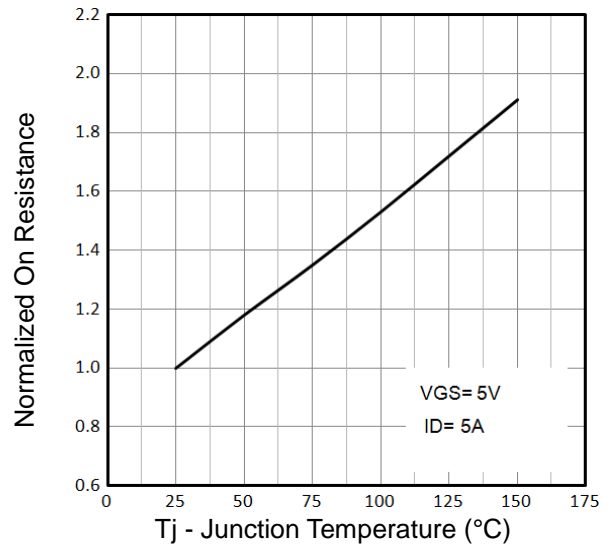


Fig4. Normalized On-Resistance Vs. Temperature

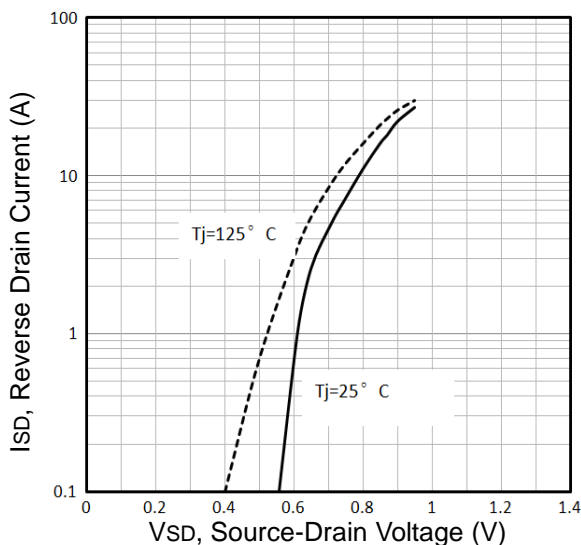


Fig5. Typical Source-Drain Diode Forward Voltage

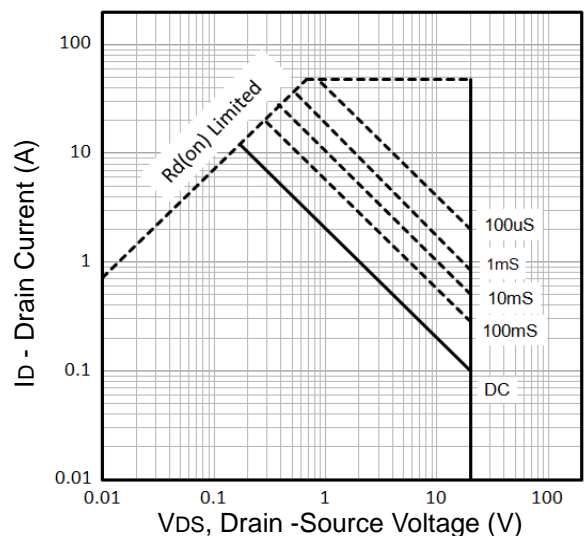


Fig6. Maximum Safe Operating Area

Typical Characteristics

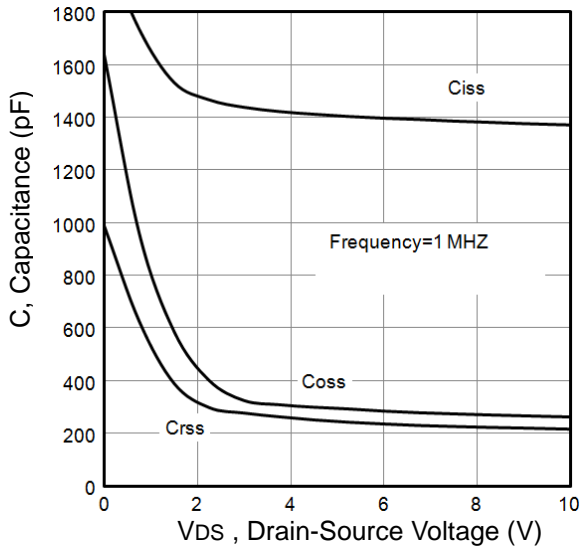


Fig7. Typical Capacitance Vs. Drain-Source Voltage

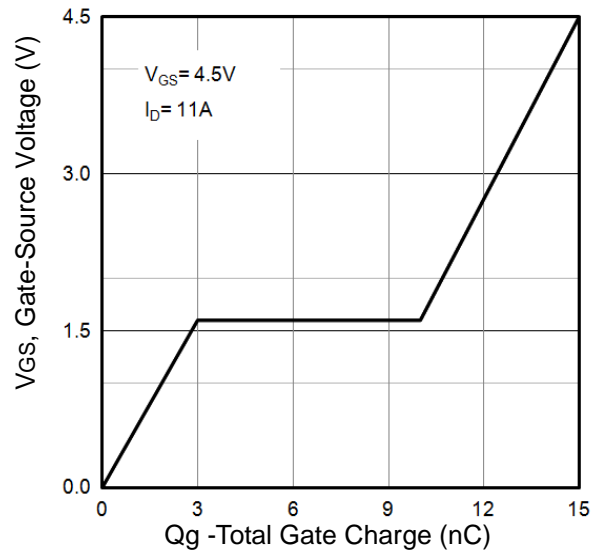


Fig8. Typical Gate Charge Vs. Gate-Source

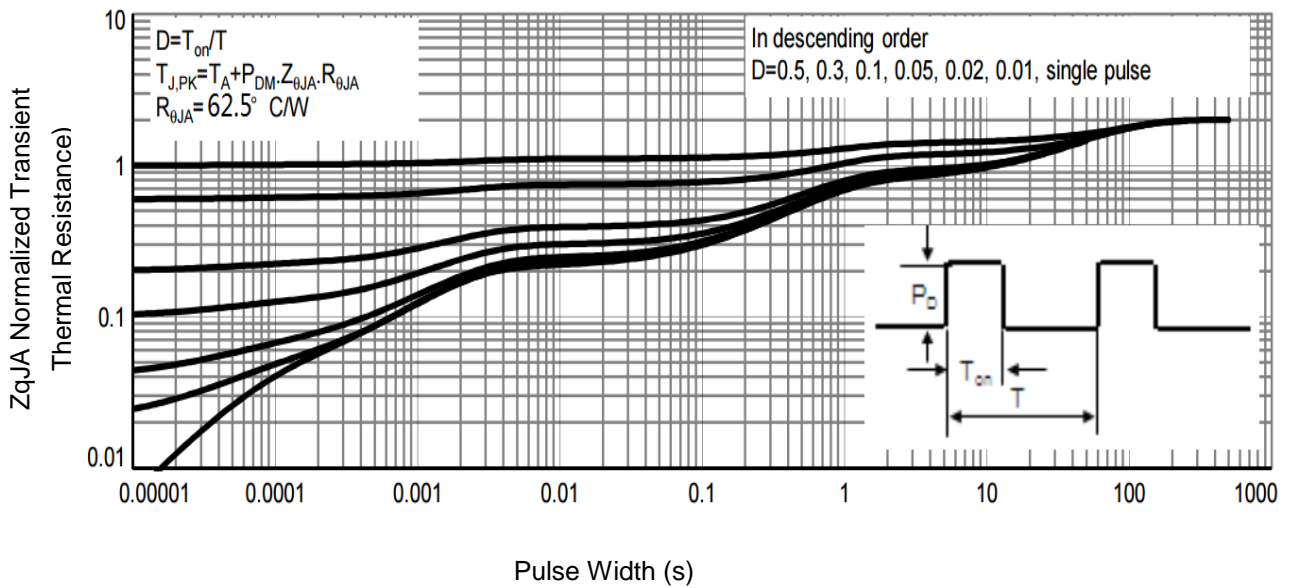


Fig9. Normalized Maximum Transient Thermal Impedance

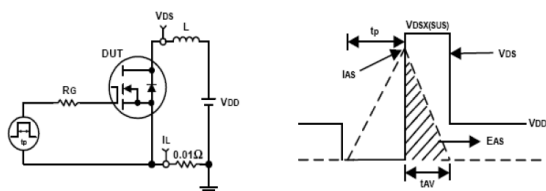


Fig10. Unclamped Inductive Test Circuit and waveforms

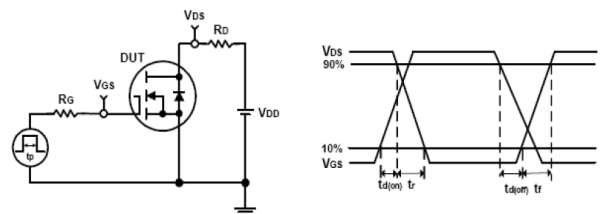
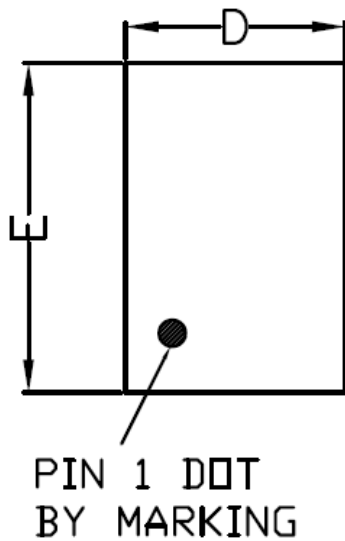
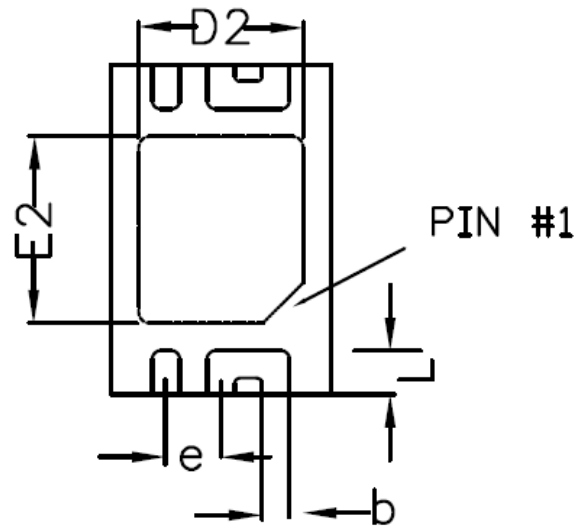


Fig11. Switching Time Test Circuit and waveforms

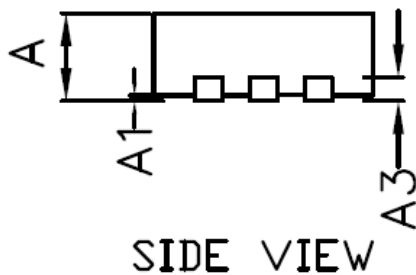
TDFN2x3-6L Package Outline Data



TOP VIEW



BOTTOM VIEW



SIDE VIEW

DIMENSIONS ( unit : mm )

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.80	0.85	A <sub>1</sub>	0.00	--	0.05
A <sub>3</sub>	0.195	0.200	0.211	D	1.95	2.00	2.05
D <sub>2</sub>	1.45	1.50	1.55	E	2.95	3.00	3.05
E <sub>2</sub>	1.65	1.70	1.75	b	0.20	0.25	0.30
L	0.35	0.40	0.45	e	0.50BSC		